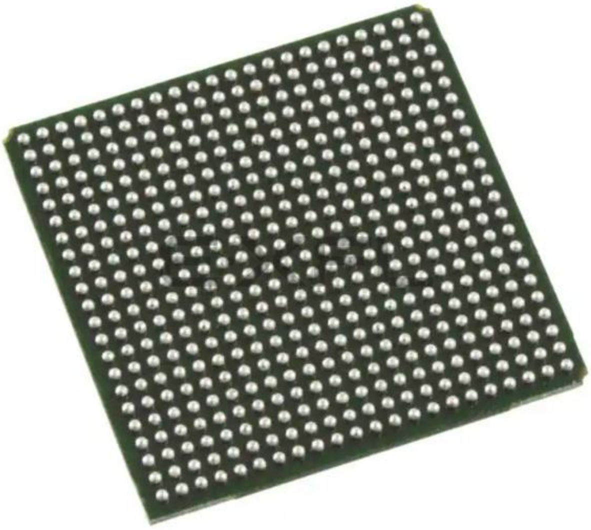
Lattice Semiconductor Corporation - LFE2-50SE-5F484C Datasheet



Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	6000
Number of Logic Elements/Cells	48000
Total RAM Bits	396288
Number of I/O	339
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-50se-5f484c

Figure 2-1. Simplified Block Diagram, ECP2-6 Device (Top Level)

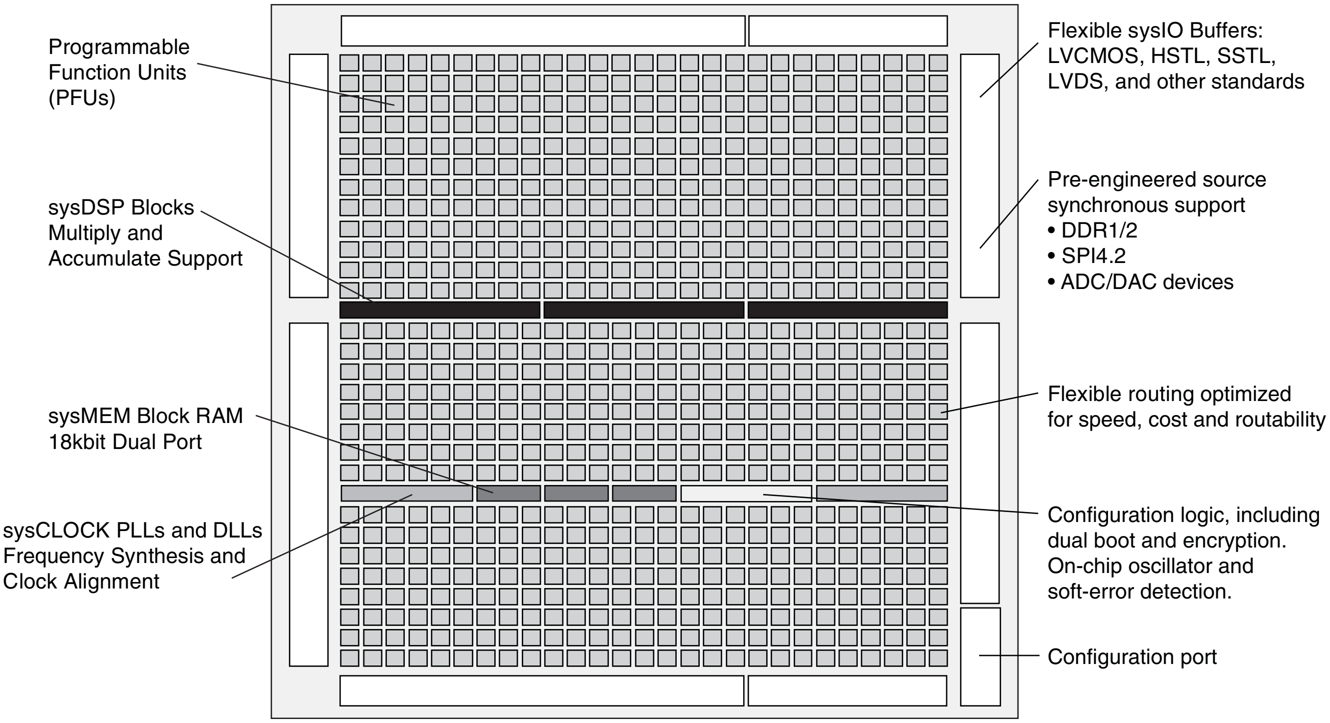


Figure 2-2. Simplified Block Diagram, ECP2M20 Device (Top Level)

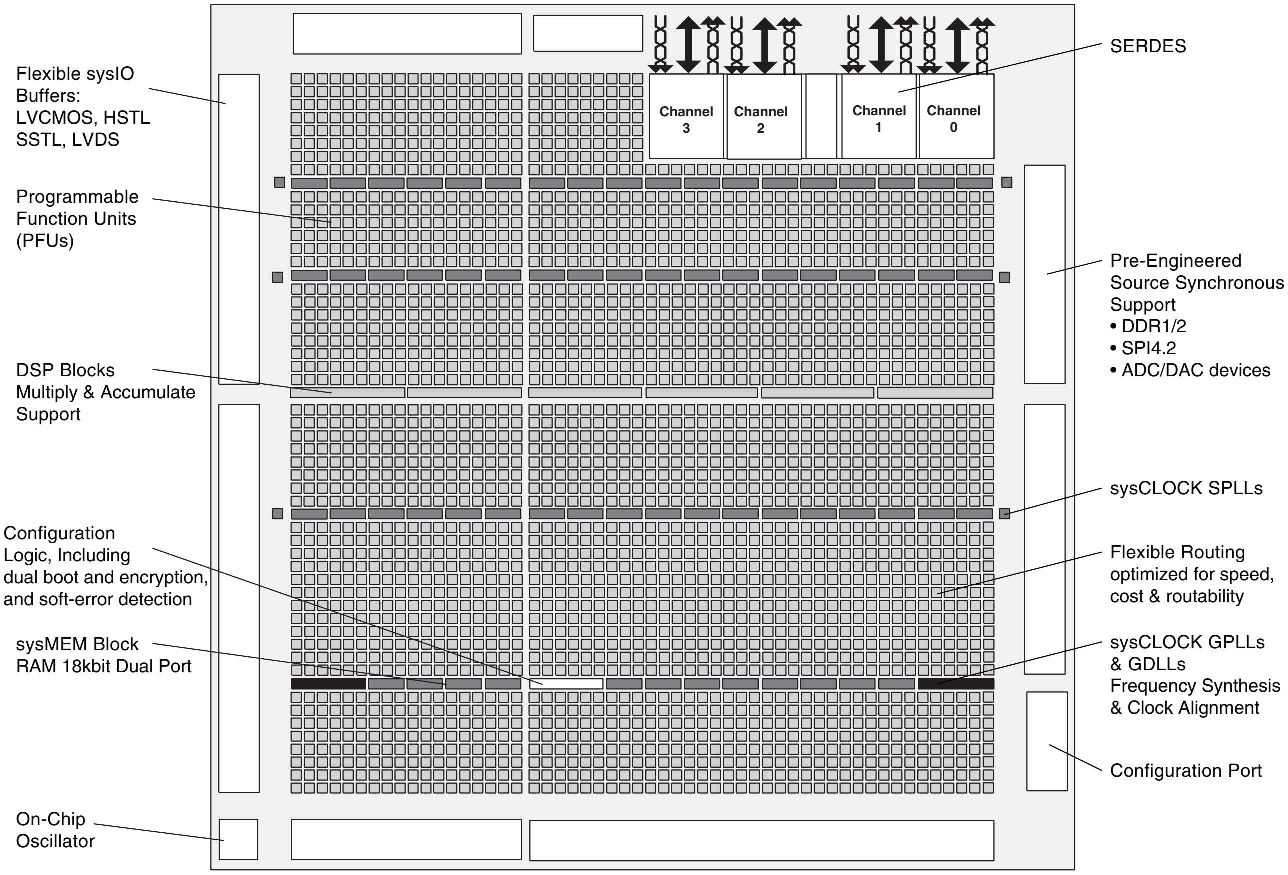
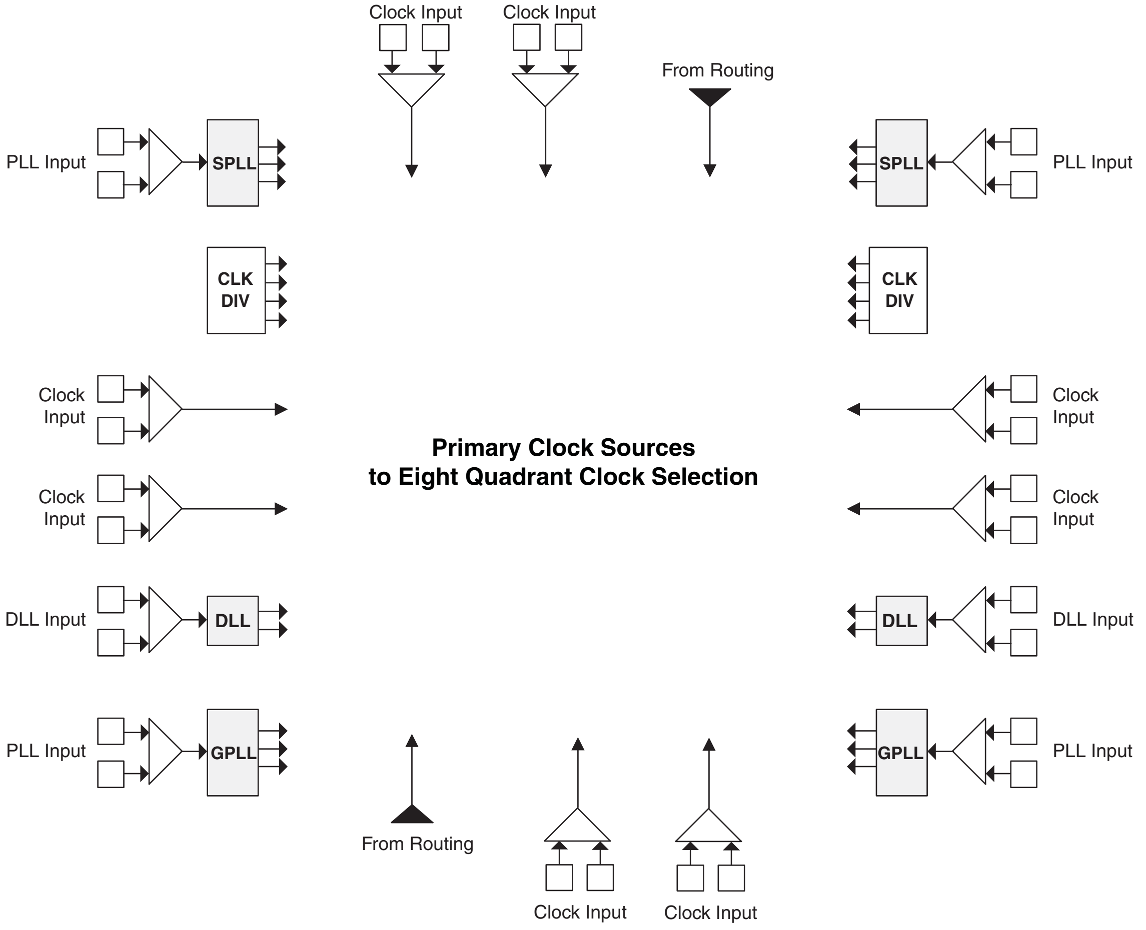


Figure 2-10. Primary Clock Sources for ECP2-50



Note: This diagram shows sources for the ECP2-50 device. Smaller LatticeECP2 devices have fewer SPLLs. All LatticeECP2M devices have six SPLLs.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed for checking soft errors (SED) in SRAM. SED can be run on a programmed device when the user logic is not active. If a soft error occurs, during user mode (normal operation) the device can be programmed to either reload from a known good boot image or generate an error signal.

For further information about Soft Error Detect (SED) support, please see the list of additional technical documentation at the end of this data sheet.

External Resistor

LatticeECP2/M devices require a single external, 10K ohm ±1% value between the XRES pin and ground. Device configuration will not be completed if this resistor is missing. There is no boundary scan register on the external resistor pad.

On-Chip Oscillator

Every LatticeECP2/M device has an internal CMOS oscillator which is used to derive a Master Clock for configuration. The oscillator and the Master Clock run continuously and are available to user logic after configuration is completed. The software default value of the Master Clock is 2.5MHz. Table 2-16 lists all the available Master Configuration Clock frequencies for normal non-encrypted mode and encrypted mode. When a different Master Clock is selected during the design process, the following sequence takes place:

1. Device powers up with a Master Clock frequency of 3.1MHz.
2. During configuration, users select a different master clock frequency.
3. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.
4. If the user does not select a master clock frequency, then the configuration bitstream defaults to the Master Clock frequency of 2.5MHz.

This internal CMOS oscillator is available to the user by routing it as an input clock to the clock tree. For further information about the use of this oscillator for configuration or user mode, please see the list of additional technical documentation at the end of this data sheet.

Table 2-16. Selectable Master Clock (CCLK) Frequencies During Configuration

Non-Encrypted Mode CCLK (MHz)			Encrypted Mode CCLK (MHz)
2.5[1]	13.0	45.0	2.5[1]
4.3	15.0	55.0	5.4
5.4	20.0	60.0	10.0
6.9	26.0	—	—
8.1	30.0	—	—
9.2	34.0	—	—
10.0	41.0	130.0	—

1. Software default frequency.

Density Shifting

The LatticeECP2/M family is designed to ensure that different density devices in the same family and in the same package have the same pinout. Furthermore, the architecture ensures a high success rate when performing design migration from lower density devices to higher density devices. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likelihood of success in each case. Design migration between LatticeECP2 and LatticeECP2M families is not possible. For specific requirements relating to sysCONFIG pins of the ECP2M50, M70 and M100, see the Logic Signal Connections tables.

Register-to-Register Performance (Continued)

Function	-7 Timing	Units
36x36 Multiplier (All Registers)	372	MHz
18x18 Multiplier/Accumulate (Input and Output Registers)	295	MHz
18x18 Multiplier-Add/Sub-Sum (All Registers)	420	MHz
DSP IP Functions		
16-Tap Fully-Parallel FIR Filter	304	MHz
1024-pt, Radix 4, Decimation in Frequency FFT	227	MHz
8x8 Matrix Multiplier	223	MHz

Derating Timing Tables

Logic timing provided in the following sections of this data sheet and the Diamond design tool are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best case process, can be much better than the values given in the tables. The Diamond design tool can provide logic timing numbers at a particular temperature and voltage.

LatticeECP2/M External Switching Characteristics[9] (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{H_DELE}	Clock to Data Hold - PIO Input Register with Input Data Delay	LFE2-6	0.00	—	0.00	—	0.00	—	ns
		LFE2-12	0.00	—	0.00	—	0.00	—	ns
		LFE2-20	0.00	—	0.00	—	0.00	—	ns
		LFE2-35	0.00	—	0.00	—	0.00	—	ns
		LFE2-50	0.00	—	0.00	—	0.00	—	ns
		LFE2-70	0.00	—	0.00	—	0.00	—	ns
		LFE2M20	0.00	—	0.00	—	0.00	—	ns
		LFE2M35	0.00	—	0.00	—	0.00	—	ns
		LFE2M50	0.00	—	0.00	—	0.00	—	ns
		LFE2M70	0.00	—	0.00	—	0.00	—	ns
		LFE2M100	0.00	—	0.00	—	0.00	—	ns
f_{MAX_IOE}	Clock Frequency of I/O and PFU Register	ECP2/M	—	420	—	357	—	311	MHz
General I/O Pin Parameters (using Primary Clock with PLL)[1]									
t_{COPLL}[10]	Clock to Output - PIO Output Register	LFE2-6	—	2.30	—	2.60	—	2.80	ns
		LFE2-12	—	2.30	—	2.60	—	2.80	ns
		LFE2-20	—	2.30	—	2.60	—	2.80	ns
		LFE2-35	—	2.30	—	2.60	—	2.80	ns
		LFE2-50	—	2.30	—	2.60	—	2.80	ns
		LFE2-70	—	2.30	—	2.60	—	2.80	ns
		LFE2M20	—	2.30	—	2.60	—	2.80	ns
		LFE2M35	—	2.30	—	2.60	—	2.80	ns
		LFE2M50	—	2.60	—	2.90	—	3.10	ns
		LFE2M70	—	2.60	—	2.90	—	3.10	ns
		LFE2M100	—	2.70	—	3.00	—	3.20	ns
t_{SUPLL}	Clock to Data Setup - PIO Input Register	LFE2-6	0.70	—	0.80	—	0.90	—	ns
		LFE2-12	0.70	—	0.80	—	0.90	—	ns
		LFE2-20	0.70	—	0.80	—	0.90	—	ns
		LFE2-35	0.70	—	0.80	—	0.90	—	ns
		LFE2-50	0.70	—	0.80	—	0.90	—	ns
		LFE2-70	0.70	—	0.80	—	0.90	—	ns
		LFE2M20	0.70	—	0.80	—	0.90	—	ns
		LFE2M35	0.70	—	0.80	—	0.90	—	ns
		LFE2M50	0.70	—	0.80	—	0.90	—	ns
		LFE2M70	0.70	—	0.80	—	0.90	—	ns
		LFE2M100	0.80	—	0.90	—	1.00	—	ns

SERDES High-Speed Data Transmitter (LatticeECP2M Family Only)[1, 2]

Table 3-7. Serial Output Timing and Levels

Symbol	Description	Frequency	Min.	Typ.	Max.	Units
$V_{TX-DIFF-P-P-1}$	Differential swing (1V setting)[1, 2]	0.25 to 3.125 Gbps	0.79	0.99	1.19	V, p-p
$V_{TX-DIFF-P-P-1.25}$	Differential swing (1.25V setting)[1, 2]	0.25 to 3.125 Gbps	1.00	1.25	1.50	V, p-p
$V_{TX-DIFF-P-P-1.3}$	Differential swing (1.3V setting)[1, 2]	0.25 to 3.125 Gbps	1.04	1.30	1.56	V, p-p
$V_{TX-DIFF-P-P-1.35}$	Differential swing (1.35V setting)[1, 2]	0.25 to 3.125 Gbps	1.08	1.35	1.62	V, p-p
V_{OCM}	Output common mode voltage	—	V_{CCOB} - 0.75	V_{CCOB} - 0.60	V_{CCOB} - 0.45	V
T_{TX-R}	Rise time (20% to 80%)	—	—	70	—	ps
T_{TX-F}	Fall time (80% to 20%)	—	—	70	—	ps
$Z_{TX-OI-SE}$	Output impedance 50/75/HiZ K Ohms (single-ended)	—	—	50/70 HiZ	—	Ohms
R_{TX-RL}	Return loss (with package)	—	—	9	—	dB

1. All measurements are with 50 ohm impedance.
2. See TN1124, LatticeECP2M SERDES/PCS Usage Guide for actual binary settings.

Table 3-8. Channel Output Jitter - x10 Mode

Description	Frequency	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	—	0.08	0.12	UI, p-p
Random	3.125 Gbps	—	0.22	0.38	UI, p-p
Total	3.125 Gbps	—	0.33	0.43	UI, p-p
Deterministic	2.5 Gbps	—	0.08	0.17	UI, p-p
Random	2.5 Gbps	—	0.20	0.25	UI, p-p
Total	2.5 Gbps	—	0.25	0.35	UI, p-p
Deterministic	1.25 Gbps	—	0.03	0.10	UI, p-p
Random	1.25 Gbps	—	0.14	0.19	UI, p-p
Total	1.25 Gbps	—	0.17	0.24	UI, p-p
Deterministic	250 Mbps	—	0.04	0.17	UI, p-p
Random	250 Mbps	—	0.12	0.13	UI, p-p
Total	250 Mbps	—	0.15	0.29	UI, p-p

Note: Values are measured with PRBS 2^7-1, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, reference clock at x10 mode.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
46	PL28B	6	LDQ28	C (LVDS)*	PL42B	6	LDQ42	C (LVDS)*
47	PL30A	6	LDQ28		PL44A	6	LDQ42	
48	TCK	-			TCK	-		
49	TDI	-			TDI	-		
50	TDO	-			TDO	-		
51	VCCJ	-			VCCJ	-		
52	TMS	-			TMS	-		
53	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
54	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
55	VCCIO5	5			VCCIO5	5		
56	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
57	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
58	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
59	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
60	GND	-			GND	-		
61	PB12A	5	BDQ15	T	PB12A	5	BDQ15	T
62	PB12B	5	BDQ15	C	PB12B	5	BDQ15	C
63	VCCIO5	5			VCCIO5	5		
64	PB16A	5	BDQ15	T	PB16A	5	BDQ15	T
65	PB16B	5	BDQ15	C	PB16B	5	BDQ15	C
66	PB18A	5	BDQ15	T	PB18A	5	BDQ15	T
67	PB18B	5	BDQ15	C	PB18B	5	BDQ15	C
68	GND	-			GND	-		
69	PB20A	5	BDQ24	T	PB30A	5	BDQ33	T
70	VCCAUX	-			VCCAUX	-		
71	PB20B	5	BDQ24	C	PB30B	5	BDQ33	C
72	PB22A	5	BDQ24	T	PB32A	5	BDQ33	T
73	PB22B	5	BDQ24	C	PB32B	5	BDQ33	C
74	VCC	-			VCC	-		
75	PB26A	5	PCLKT5_0/BDQ24	T	PB35A	5	PCLKT5_0/BDQ33	T
76	PB26B	5	PCLKC5_0/BDQ24	C	PB35B	5	PCLKC5_0/BDQ33	C
77	GND	-			GND	-		
78	PB31A	4	PCLKT4_0/BDQ33	T	PB40A	4	PCLKT4_0/BDQ42	T
79	PB31B	4	PCLKC4_0/BDQ33	C	PB40B	4	PCLKC4_0/BDQ42	C
80	VCC	-			VCC	-		
81	GND	-			GND	-		
82	PB34A	4	BDQ33	T	PB42A	4	BDQS42	T
83	PB34B	4	BDQ33	C	PB42B	4	BDQ42	C
84	PB36A	4	BDQ33	T	PB44A	4	BDQ42	T
85	PB36B	4	BDQ33	C	PB44B	4	BDQ42	C
86	VCCAUX	-			VCCAUX	-		
87	PB40A	4	BDQ42	T	PB50A	4	BDQ51	T
88	PB40B	4	BDQ42	C	PB50B	4	BDQ51	C
89	GND	-			GND	-		
90	PB42A	4	BDQS42	T	PB52A	4	BDQ51	T
91	PB42B	4	BDQ42	C	PB52B	4	BDQ51	C

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W20	CFG0	8			CFG0	8		
V20	PROGRAMN	8			PROGRAMN	8		
W22	CCLK	8			CCLK	8		
V22	INITN	8			INITN	8		
V21	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
R16	PR58B	8	WRITEN	C	PR77B	8	WRITEN	C
R17	PR58A	8	CS1N	T	PR77A	8	CS1N	T
U19	PR57B	8	CSN	C	PR76B	8	CSN	C
U20	PR57A	8	D0/SPIFASTN	T	PR76A	8	D0/SPIFASTN	T
VCCIO	VCCIO8	8			VCCIO	8		
U22	PR56B	8	D1	C	PR75B	8	D1	C
U21	PR56A	8	D2	T	PR75A	8	D2	T
T20	PR55B	8	D3	C	PR74B	8	D3	C
GNDIO	GNDIO8	-			GNDIO8	-		
T19	PR55A	8	D4	T	PR74A	8	D4	T
T17	PR54B	8	D5	C	PR73B	8	D5	C
T18	PR54A	8	D6	T	PR73A	8	D6	T
T21	PR53B	8	D7/SPID0	C	PR72B	8	D7/SPID0	C
VCCIO	VCCIO8	8			VCCIO	8		
T22	PR53A	8	DI/CSSPI0N	T	PR72A	8	DI/CSSPI0N	T
R18	PR52B	8	DOUT/CSON	C	PR71B	8	DOUT/CSON	C
R19	PR52A	8	BUSY/SISPI	T	PR71A	8	BUSY/SISPI	T
GNDIO	GNDIO3	-			GNDIO3	-		
VCCIO	VCCIO3	3			VCCIO	3		
R22	PR47B	3	RDQ48	C	PR66B	3	RDQ67	C
R21	PR47A	3	RDQ48	T	PR66A	3	RDQ67	T
P18	PR46B	3	RDQ48	C (LVDS)*	PR65B	3	RDQ67	C (LVDS)*
P19	PR46A	3	RDQ48	T (LVDS)*	PR65A	3	RDQ67	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO	3		
R20	PR45B	3	RLM0_GPLLC_FB_A/RDQ48	C	PR64B	3	RLM0_GPLLC_FB_A/RDQ67	C
P22	PR45A	3	RLM0_GPLLT_FB_A/RDQ48	T	PR64A	3	RLM0_GPLLT_FB_A/RDQ67	T
P21	PR44B	3	RLM0_GPLLC_IN_A**/RDQ48	C (LVDS)*	PR63B	3	RLM0_GPLLC_IN_A**/RDQ67	C (LVDS)*
N21	PR44A	3	RLM0_GPLLT_IN_A**/RDQ48	T (LVDS)*	PR63A	3	RLM0_GPLLT_IN_A**/RDQ67	T (LVDS)*
N17	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
N22	PR42B	3	RLM0_GDLLC_FB_A/RDQ39	C	PR61B	3	RLM0_GDLLC_FB_A/RDQ58	C
N20	PR42A	3	RLM0_GDLLT_FB_A/RDQ39	T	PR61A	3	RLM0_GDLLT_FB_A/RDQ58	T
GNDIO	GNDIO3	-			GNDIO3	-		
M22	PR41B	3	RLM0_GDLLC_IN_A**/RDQ39	C (LVDS)*	PR60B	3	RLM0_GDLLC_IN_A**/RDQ58	C (LVDS)*
M21	PR41A	3	RLM0_GDLLT_IN_A**/RDQ39	T (LVDS)*	PR60A	3	RLM0_GDLLT_IN_A**/RDQ58	T (LVDS)*
N19	PR40B	3	RDQ39	C	PR59B	3	RDQ58	C
M19	PR40A	3	RDQ39	T	PR59A	3	RDQ58	T
VCCIO	VCCIO3	3			VCCIO	3		
GNDIO	GNDIO3	-			GNDIO3	-		
L22	PR30B	3	RDQ31	C	PR49B	3	RDQ50	C
K22	PR30A	3	RDQ31	T	PR49A	3	RDQ50	T

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
J22	PR29B	3	RDQ31	C (LVDS)*	PR48B	3	RDQ50	C (LVDS)*
H22	PR29A	3	RDQ31	T (LVDS)*	PR48A	3	RDQ50	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO	3		
M20	PR28B	3	VREF2_3/RDQ31	C	PR47B	3	VREF2_3/RDQ50	C
L21	PR28A	3	VREF1_3/RDQ31	T	PR47A	3	VREF1_3/RDQ50	T
K21	PR27B	3	PCLKC3_0/RDQ31	C (LVDS)*	PR46B	3	PCLKC3_0/RDQ50	C (LVDS)*
J21	PR27A	3	PCLKT3_0/RDQ31	T (LVDS)*	PR46A	3	PCLKT3_0/RDQ50	T (LVDS)*
M18	PR25B	2	PCLKC2_0/RDQ22	C	PR44B	2	PCLKC2_0/RDQ41	C
L17	PR25A	2	PCLKT2_0/RDQ22	T	PR44A	2	PCLKT2_0/RDQ41	T
GNDIO	GNDIO2	-			GNDIO2	-		
L19	PR24B	2	RDQ22	C (LVDS)*	PR43B	2	RDQ41	C (LVDS)*
L20	PR24A	2	RDQ22	T (LVDS)*	PR43A	2	RDQ41	T (LVDS)*
L18	PR23B	2	RDQ22	C	PR42B	2	RDQ41	C
K17	PR23A	2	RDQ22	T	PR42A	2	RDQ41	T
VCCIO	VCCIO2	2			VCCIO	2		
K18	PR22B	2	RDQ22	C (LVDS)*	PR41B	2	RDQ41	C (LVDS)*
K19	PR22A	2	RDQS22	T (LVDS)*	PR41A	2	RDQS41	T (LVDS)*
G22	PR21B	2	RDQ22	C	PR40B	2	RDQ41	C
GNDIO	GNDIO2	-			GNDIO2	-		
F22	PR21A	2	RDQ22	T	PR40A	2	RDQ41	T
J17	PR20B	2	RDQ22	C (LVDS)*	PR39B	2	RDQ41	C (LVDS)*
J18	PR20A	2	RDQ22	T (LVDS)*	PR39A	2	RDQ41	T (LVDS)*
K20	PR19B	2	RDQ22	C	PR38B	2	RDQ41	C
VCCIO	VCCIO2	2			VCCIO	2		
J19	PR19A	2	RDQ22	T	PR38A	2	RDQ41	T
H21	PR18B	2	RDQ22	C (LVDS)*	PR37B	2	RDQ41	C (LVDS)*
G21	PR18A	2	RDQ22	T (LVDS)*	PR37A	2	RDQ41	T (LVDS)*
-	-	-			GNDIO2	-		
-	-	-			VCCIO	2		
H17	NC	-			PR26B	2	RUM0_SPLLC_FB_A/RDQ24	C
H16	NC	-			PR26A	2	RUM0_SPLLT_FB_A/RDQ24	T
H20	NC	-			PR25B	2	RUM0_SPLLC_IN_A/RDQ24	C
H18	NC	-			PR25A	2	RUM0_SPLLT_IN_A/RDQ24	T
-	-	-			GNDIO2	-		
-	-	-			VCCIO	2		
F21	PR17B	2	RDQ14	C	PR19B	2	RDQ16	C
GNDIO	GNDIO2	-			GNDIO2	-		
E22	PR17A	2	RDQ14	T	PR19A	2	RDQ16	T
D22	PR16B	2	RDQ14	C (LVDS)*	PR18B	2	RDQ16	C (LVDS)*
E21	PR16A	2	RDQ14	T (LVDS)*	PR18A	2	RDQ16	T (LVDS)*
G20	PR15B	2	RDQ14	C	PR17B	2	RDQ16	C
VCCIO	VCCIO2	2			VCCIO	2		
F20	PR15A	2	RDQ14	T	PR17A	2	RDQ16	T
H19	PR14B	2	RDQ14	C (LVDS)*	PR16B	2	RDQ16	C (LVDS)*
G19	PR14A	2	RDQS14	T (LVDS)*	PR16A	2	RDQS16	T (LVDS)*
GNDIO	GNDIO2	-			GNDIO2	-		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO2	-			GNDIO2	-		
L21	PR43B	2	RDQ41	C (LVDS)*	PR56B	2	RDQ54	C (LVDS)*
K22	PR43A	2	RDQ41	T (LVDS)*	PR56A	2	RDQ54	T (LVDS)*
M24	PR42B	2	RDQ41	C	PR55B	2	RDQ54	C
N23	PR42A	2	RDQ41	T	PR55A	2	RDQ54	T
VCCIO	VCCIO2	2			VCCIO2	2		
K26	PR41B	2	RDQ41	C (LVDS)*	PR54B	2	RDQ54	C (LVDS)*
K25	PR41A	2	RDQS41	T (LVDS)*	PR54A	2	RDQS54	T (LVDS)*
M20	PR40B	2	RDQ41	C	PR53B	2	RDQ54	C
GND	GNDIO2	-			GNDIO2	-		
M19	PR40A	2	RDQ41	T	PR53A	2	RDQ54	T
L22	PR39B	2	RDQ41	C (LVDS)*	PR52B	2	RDQ54	C (LVDS)*
M22	PR39A	2	RDQ41	T (LVDS)*	PR52A	2	RDQ54	T (LVDS)*
K21	PR38B	2	RDQ41	C	PR51B	2	RDQ54	C
VCCIO	VCCIO2	2			VCCIO2	2		
M21	PR38A	2	RDQ41	T	PR51A	2	RDQ54	T
K24	PR37B	2	RDQ41	C (LVDS)*	PR50B	2	RDQ54	C (LVDS)*
J24	PR37A	2	RDQ41	T (LVDS)*	PR50A	2	RDQ54	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
VCCIO	VCCIO2	2			VCCIO2	2		
L20	VCCPLL	2			NC	-		
GND	GNDIO2	-			GNDIO2	-		
J26	PR26B	2	RUM0_SPLLC_FB_A/RDQ24	C	PR39B	2	RUM0_SPLLC_FB_A/RDQ37	C
J25	PR26A	2	RUM0_SPLLT_FB_A/RDQ24	T	PR39A	2	RUM0_SPLLT_FB_A/RDQ37	T
J23	PR25B	2	RUM0_SPLLC_IN_A/RDQ24	C	PR38B	2	RUM0_SPLLC_IN_A/RDQ37	C
K23	PR25A	2	RUM0_SPLLT_IN_A/RDQ24	T	PR38A	2	RUM0_SPLLT_IN_A/RDQ37	T
VCCIO	VCCIO2	2			VCCIO2	2		
H26	PR24B	2	RDQ24	C (LVDS)*	PR37B	2	RDQ37	C (LVDS)*
H25	PR24A	2	RDQS24***	T (LVDS)*	PR37A	2	RDQS37***	T (LVDS)*
H24	PR23B	2	RDQ24	C	PR36B	2	RDQ37	C
GND	GNDIO2	-			GNDIO2	-		
H23	PR23A	2	RDQ24	T	PR36A	2	RDQ37	T
VCCIO	VCCIO2	2			VCCIO2	2		
G26	PR19B	2	RDQ16	C	PR32B	2	RDQ29	C
GND	GNDIO2	-			GNDIO2	-		
G25	PR19A	2	RDQ16	T	PR32A	2	RDQ29	T
F26	PR18B	2	RDQ16	C (LVDS)*	PR31B	2	RDQ29	C (LVDS)*
F25	PR18A	2	RDQ16	T (LVDS)*	PR31A	2	RDQ29	T (LVDS)*
K20	PR17B	2	RDQ16	C	PR30B	2	RDQ29	C
VCCIO	VCCIO2	2			VCCIO2	2		
L19	PR17A	2	RDQ16	T	PR30A	2	RDQ29	T
E26	PR16B	2	RDQ16	C (LVDS)*	PR29B	2	RDQ29	C (LVDS)*
E25	PR16A	2	RDQS16	T (LVDS)*	PR29A	2	RDQS29	T (LVDS)*
GND	GNDIO2	-			GNDIO2	-		
J22	PR15B	2	RDQ16	C	PR28B	2	RDQ29	C
H22	PR15A	2	RDQ16	T	PR28A	2	RDQ29	T

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

	LFE2-50E/SE				LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A2	GND	-			GND	-		
A25	GND	-			GND	-		
AA18	GND	-			GND	-		
AA24	GND	-			GND	-		
AA3	GND	-			GND	-		
AA9	GND	-			GND	-		
AD11	GND	-			GND	-		
AD16	GND	-			GND	-		
AD21	GND	-			GND	-		
AD6	GND	-			GND	-		
AE1	GND	-			GND	-		
AE26	GND	-			GND	-		
AF2	GND	-			GND	-		
AF25	GND	-			GND	-		
B1	GND	-			GND	-		
B26	GND	-			GND	-		
C11	GND	-			GND	-		
C16	GND	-			GND	-		
C21	GND	-			GND	-		
C6	GND	-			GND	-		
F18	GND	-			GND	-		
F24	GND	-			GND	-		
F3	GND	-			GND	-		
F9	GND	-			GND	-		
J13	GND	-			GND	-		
J14	GND	-			GND	-		
J21	GND	-			GND	-		
J6	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K13	GND	-			GND	-		
K14	GND	-			GND	-		
K16	GND	-			GND	-		
K17	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L16	GND	-			GND	-		
L17	GND	-			GND	-		
L24	GND	-			GND	-		
L3	GND	-			GND	-		
M13	GND	-			GND	-		
M14	GND	-			GND	-		
N10	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N14	GND	-			GND	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AD18	PB66A	4	BDQ69	T
AF18	PB66B	4	BDQ69	C
AC18	PB67A	4	BDQ69	T
AE18	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4		
AG19	PB68A	4	BDQ69	T
AH19	PB68B	4	BDQ69	C
GND	GNDIO4	-		
AE19	PB69A	4	BDQS69	T
AF19	PB69B	4	BDQ69	C
AC19	PB70A	4	BDQ69	T
AD19	PB70B	4	BDQ69	C
AJ19	PB71A	4	BDQ69	T
AK19	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4		
AF20	PB72A	4	BDQ69	T
AH20	PB72B	4	BDQ69	C
AE20	PB73A	4	BDQ69	T
AG20	PB73B	4	BDQ69	C
GND	GNDIO4	-		
AD20	PB74A	4	BDQ78	T
AC20	PB74B	4	BDQ78	C
AH21	PB75A	4	BDQ78	T
AF21	PB75B	4	BDQ78	C
AJ20	PB76A	4	BDQ78	T
VCCIO	VCCIO4	4		
AK20	PB76B	4	BDQ78	C
AG21	PB77A	4	BDQ78	T
AE21	PB77B	4	BDQ78	C
AD21	PB78A	4	BDQS78	T
GND	GNDIO4	-		
AC21	PB78B	4	BDQ78	C
AD22	PB79A	4	BDQ78	T
AB21	PB79B	4	BDQ78	C
AJ21	PB80A	4	BDQ78	T
VCCIO	VCCIO4	4		
AK21	PB80B	4	BDQ78	C
GND	GNDIO4	-		
VCCIO	VCCIO4	4		
AJ25	PB87A	4	BDQS87***	T
AK24	PB87B	4	BDQ87	C
AJ24	PB88A	4	BDQ87	T
AK25	PB88B	4	BDQ87	C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AG4	NC	-		
AG8	NC	-		
AH1	NC	-		
AH16	NC	-		
AH2	NC	-		
AH26	NC	-		
AH27	NC	-		
AH29	NC	-		
AH30	NC	-		
AH4	NC	-		
AJ1	NC	-		
AJ2	NC	-		
AJ27	NC	-		
AJ28	NC	-		
AJ29	NC	-		
AJ3	NC	-		
AJ30	NC	-		
AK2	NC	-		
AK27	NC	-		
AK28	NC	-		
AK29	NC	-		
AK3	NC	-		
B1	NC	-		
B2	NC	-		
B3	NC	-		
B30	NC	-		
B4	NC	-		
B5	NC	-		
C1	NC	-		
C2	NC	-		
C29	NC	-		
C30	NC	-		
C4	NC	-		
D13	NC	-		
D18	NC	-		
D23	NC	-		
D28	NC	-		
D29	NC	-		
D3	NC	-		
D30	NC	-		
D4	NC	-		
E25	NC	-		
E26	NC	-		

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
E27	NC	-		
E28	NC	-		
E29	NC	-		
E3	NC	-		
E30	NC	-		
E4	NC	-		
E5	NC	-		
E6	NC	-		
F25	NC	-		
F5	NC	-		
F6	NC	-		
G6	NC	-		
G7	NC	-		
K10	NC	-		
K9	NC	-		
N27	NC	-		
N4	NC	-		
R1	NC	-		
R2	NC	-		
V27	NC	-		
V4	NC	-		
P22	VCCPLL	-		
P8	VCCPLL	-		
T22	VCCPLL	-		
Y7	VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.
** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.
***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO4	-			GNDIO4	-		
AA15	PB42B	4	BDQ42	C	PB60B	4	BDQ60	C
V15	PB43A	4	BDQ42	T	PB61A	4	BDQ60	T
U15	PB43B	4	BDQ42	C	PB61B	4	BDQ60	C
AB16	PB44A	4	BDQ42	T	PB62A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
AA16	PB44B	4	BDQ42	C	PB62B	4	BDQ60	C
AB17	PB45A	4	BDQ42	T	PB63A	4	BDQ60	T
AA17	PB45B	4	BDQ42	C	PB63B	4	BDQ60	C
Y15	PB46A	4	BDQ42	T	PB64A	4	BDQ60	T
GNDIO	GNDIO4	-			GNDIO4	-		
W15	PB46B	4	BDQ42	C	PB64B	4	BDQ60	C
AB20	PB47A	4	BDQ51	T	PB65A	4	BDQ69	T
AB21	PB47B	4	BDQ51	C	PB65B	4	BDQ69	C
AA21	PB48A	4	BDQ51	T	PB66A	4	BDQ69	T
AA20	PB48B	4	BDQ51	C	PB66B	4	BDQ69	C
AB19	PB49A	4	BDQ51	T	PB67A	4	BDQ69	T
AB18	PB49B	4	BDQ51	C	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
Y22	PB50A	4	BDQ51	T	PB68A	4	BDQ69	T
Y21	PB50B	4	BDQ51	C	PB68B	4	BDQ69	C
GNDIO	GNDIO4	-			GNDIO4	-		
Y17	PB51A	4	BDQS51	T	PB69A	4	BDQS69	T
Y18	PB51B	4	BDQ51	C	PB69B	4	BDQ69	C
Y16	PB52A	4	BDQ51	T	PB70A	4	BDQ69	T
W17	PB52B	4	BDQ51	C	PB70B	4	BDQ69	C
Y19	PB53A	4	BDQ51	T	PB71A	4	BDQ69	T
Y20	PB53B	4	BDQ51	C	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
W19	PB54A	4	BDQ51	T	PB72A	4	BDQ69	T
W18	PB54B	4	BDQ51	C	PB72B	4	BDQ69	C
V17	PB55A	4	BDQ51	T	PB73A	4	BDQ69	T
V18	PB55B	4	BDQ51	C	PB73B	4	BDQ69	C
GNDIO	GNDIO4	-			GNDIO4	-		
W20	CFG2	8			CFG2	8		
V20	CFG1	8			CFG1	8		
V19	CFG0	8			CFG0	8		
V22	PROGRAMN	8			PROGRAMN	8		
W22	CCLK	8			CCLK	8		
U18	INITN	8			INITN	8		
U22	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
U20	PR53B	8	WRITEN***	C	PR68B	8	WRITEN***	C
U21	PR53A	8	CS1N***	T	PR68A	8	CS1N***	T
U17	PR52B	8	CSN***	C	PR67B	8	CSN***	C
U16	PR52A	8	D0/SPIFASTN***	T	PR67A	8	D0/SPIFASTN***	T
VCCIO	VCCIO8	8			VCCIO8	8		
T16	PR51B	8	D1***	C	PR66B	8	D1***	C

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
D2	PL9A	7	VREF2_7/LDQ6	T	PL9A	7	VREF2_7	T
D3	PL9B	7	VREF1_7/LDQ6	C	PL9B	7	VREF1_7	C
GNDIO	GNDIO7	-			GNDIO7	-		
J8	PL11A	7	LUM0_SPLLT_IN_A	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*
H7	PL11B	7	LUM0_SPLLC_IN_A	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*
E3	PL12A	7	LUM0_SPLLT_FB_A	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T
E4	PL12B	7	LUM0_SPLLC_FB_A	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C
GNDIO	GNDIO7	-			-	-		
G6	PL13A	7		T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*
F5	PL13B	7		C (LVDS)*	PL13B	7	LDQ15	C (LVDS)*
E2	PL14A	7		T	PL14A	7	LDQ15	T
D1	PL14B	7		C	PL14B	7	LDQ15	C
-	-	-			GNDIO7	-		
G5	NC	-			PL15A	7	LDQS15	T (LVDS)*
G4	NC	-			PL15B	7	LDQ15	C (LVDS)*
K7	NC	-			PL16A	7	LDQ15	T
K8	NC	-			PL16B	7	LDQ15	C
E1	NC	-			PL17A	7	LDQ15	T (LVDS)*
F2	NC	-			PL17B	7	LDQ15	C (LVDS)*
F1	NC	-			PL18A	7	LDQ15	T
-	-	-			GNDIO7	-		
G3	NC	-			PL18B	7	LDQ15	C
H5	PL15A	7		T (LVDS)*	PL21A	7		T (LVDS)*
H4	PL15B	7		C (LVDS)*	PL21B	7		C (LVDS)*
J5	PL16A	7		T	PL22A	7		T
J4	PL16B	7		C	PL22B	7		C
GNDIO	GNDIO7	-			GNDIO7	-		
G2	NC	-			PL24A	7	LDQ28	T (LVDS)*
G1	NC	-			PL24B	7	LDQ28	C (LVDS)*
L9	NC	-			PL25A	7	LDQ28	T
L7	NC	-			PL25B	7	LDQ28	C
K6	NC	-			PL26A	7	LDQ28	T (LVDS)*
K5	NC	-			PL26B	7	LDQ28	C (LVDS)*
L8	NC	-			PL27A	7	LDQ28	T
L6	NC	-			PL27B	7	LDQ28	C
-	-	-			GNDIO7	-		
H3	PL18A	7		T (LVDS)*	PL28A	7	LDQS28	T (LVDS)*
H2	PL18B	7		C (LVDS)*	PL28B	7	LDQ28	C (LVDS)*
N8	PL19A	7		T	PL29A	7	LDQ28	T
M9	PL19B	7		C	PL29B	7	LDQ28	C
J3	PL20A	7		T (LVDS)*	PL30A	7	LDQ28	T (LVDS)*
VCCIO	VCCIO7	7			-	-		
J2	PL20B	7		C (LVDS)*	PL30B	7	LDQ28	C (LVDS)*
H1	PL21A	7		T	PL31A	7	LDQ28	T
GNDIO	GNDIO7	-			GNDIO7	-		
J1	PL21B	7		C	PL31B	7	LDQ28	C
-	-	-			-	-		
-	-	-			-	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
K3	VCCIO7	7			VCCIO7	7		
M10	VCCIO7	7			VCCIO7	7		
M7	VCCIO7	7			VCCIO7	7		
N10	VCCIO7	7			VCCIO7	7		
N3	VCCIO7	7			VCCIO7	7		
P10	VCCIO7	7			VCCIO7	7		
R6	VCCIO7	7			VCCIO7	7		
AA25	VCCIO8	8			VCCIO8	8		
AD28	VCCIO8	8			VCCIO8	8		
AA10	VCCAUX	-			VCCAUX	-		
AA11	VCCAUX	-			VCCAUX	-		
AA20	VCCAUX	-			VCCAUX	-		
AA21	VCCAUX	-			VCCAUX	-		
K10	VCCAUX	-			VCCAUX	-		
K11	VCCAUX	-			VCCAUX	-		
K20	VCCAUX	-			VCCAUX	-		
K21	VCCAUX	-			VCCAUX	-		
L10	VCCAUX	-			VCCAUX	-		
L11	VCCAUX	-			VCCAUX	-		
L20	VCCAUX	-			VCCAUX	-		
L21	VCCAUX	-			VCCAUX	-		
Y10	VCCAUX	-			VCCAUX	-		
Y11	VCCAUX	-			VCCAUX	-		
Y20	VCCAUX	-			VCCAUX	-		
Y21	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A13	GND	-			GND	-		
A18	GND	-			GND	-		
A24	GND	-			GND	-		
A30	GND	-			GND	-		
A7	GND	-			GND	-		
AA14	GND	-			GND	-		
AA15	GND	-			GND	-		
AA16	GND	-			GND	-		
AA17	GND	-			GND	-		
AA24	GND	-			GND	-		
AA27	GND	-			GND	-		
AA4	GND	-			GND	-		
AB24	GND	-			GND	-		
AB7	GND	-			GND	-		
AD12	GND	-			GND	-		
AD19	GND	-			GND	-		
AD27	GND	-			GND	-		
AE22	GND	-			GND	-		
AE27	GND	-			GND	-		
AE4	GND	-			GND	-		
AE9	GND	-			GND	-		
AF14	GND	-			GND	-		

LatticeECP2M Standard Series Devices, Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20E-5F484C	304	1.2V	-5	fpBGA	484	COM	20
LFE2M20E-6F484C	304	1.2V	-6	fpBGA	484	COM	20
LFE2M20E-7F484C	304	1.2V	-7	fpBGA	484	COM	20
LFE2M20E-5F256C	140	1.2V	-5	fpBGA	256	COM	20
LFE2M20E-6F256C	140	1.2V	-6	fpBGA	256	COM	20
LFE2M20E-7F256C	140	1.2V	-7	fpBGA	256	COM	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35E-5F672C	410	1.2V	-5	fpBGA	672	COM	35
LFE2M35E-6F672C	410	1.2V	-6	fpBGA	672	COM	35
LFE2M35E-7F672C	410	1.2V	-7	fpBGA	672	COM	35
LFE2M35E-5F484C	303	1.2V	-5	fpBGA	484	COM	35
LFE2M35E-6F484C	303	1.2V	-6	fpBGA	484	COM	35
LFE2M35E-7F484C	303	1.2V	-7	fpBGA	484	COM	35
LFE2M35E-5F256C	140	1.2V	-5	fpBGA	256	COM	35
LFE2M35E-6F256C	140	1.2V	-6	fpBGA	256	COM	35
LFE2M35E-7F256C	140	1.2V	-7	fpBGA	256	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50E-5F900C	410	1.2V	-5	fpBGA	900	COM	50
LFE2M50E-6F900C	410	1.2V	-6	fpBGA	900	COM	50
LFE2M50E-7F900C	410	1.2V	-7	fpBGA	900	COM	50
LFE2M50E-5F672C	372	1.2V	-5	fpBGA	672	COM	50
LFE2M50E-6F672C	372	1.2V	-6	fpBGA	672	COM	50
LFE2M50E-7F672C	372	1.2V	-7	fpBGA	672	COM	50
LFE2M50E-5F484C	270	1.2V	-5	fpBGA	484	COM	50
LFE2M50E-6F484C	270	1.2V	-6	fpBGA	484	COM	50
LFE2M50E-7F484C	270	1.2V	-7	fpBGA	484	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70E-5F1152C	436	1.2V	-5	fpBGA	1152	COM	70
LFE2M70E-6F1152C	436	1.2V	-6	fpBGA	1152	COM	70
LFE2M70E-7F1152C	436	1.2V	-7	fpBGA	1152	COM	70
LFE2M70E-5F900C	416	1.2V	-5	fpBGA	900	COM	70
LFE2M70E-6F900C	416	1.2V	-6	fpBGA	900	COM	70
LFE2M70E-7F900C	416	1.2V	-7	fpBGA	900	COM	70

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.